

#### Weidmüller Interface GmbH & Co. KG Klingenbergstraße 26

D-32758 Detmold Germany

www.weidmueller.com

#### **Product image**





Similar to illustration

High-temperature-resistant male header, 3.50 mm pitch.

- Plugging direction parallel (90°), straight 180° or angled (135°) to PCB
- Housing variants: closed side (G), screw flange (F), solder flange (LF) or snap-on solder flange (RF)
- Optimised for the SMT process
- Pin length 3.2 mm universal for all soldering methods
- Pin length 1.5 mm optimised for reflow soldering methods
- Packed either in a box (BX) or tape-on-reel (RL)
- Male header can be coded

#### General ordering data

Version	PCB plug-in connector, male header, closed side, THT/THR solder connection, 3.50 mm, Number		
	of poles: 12, 180°, Solder pin length (I): 3.2 mm,		
	tinned, black, Tape		
Order No.	<u>1928230000</u>		
Туре	SL-SMT 3.50/12/180G 3.2SN BK RL		
GTIN (EAN)	4032248577439		
Qty.	265 pc(s).		
Product data	IEC: 320 V / 15 A		
	UL: 300 V / 10 A		
Packaging	Таре		



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## **Technical data**

Depth	7.5 mm	Depth (inches)	0.295 inch
Height	14.3 mm	Height (inches)	0.563 inch
Height of lowest version	11.1 mm	Net weight	5.15 g
Width	43.4 mm	Width (inches)	1.709 inch

#### **System specifications**

Product family	OMNIMATE Signal - series BL/SL 3.50	Type of connection	Board connection	
Mounting onto the PCB	THT/THR solder	Pitch in mm (P)		
	connection		3.5 mm	
Pitch in inches (P)	0.138 inch	Outgoing elbow	180°	
Number of poles	12	Number of solder pins per pole	1	
Solder pin length (I)	3.2 mm	Solder pin length tolerance	0 / -0.3 mm	
Solder pin dimensions	d = 1.2 mm, Octagonal	Solder pin dimensions = d tolerance	0 / -0,03 mm	
Solder eyelet hole diameter (D)	1.4 mm	Solder eyelet hole diameter tolerance (D)+ 0,1 mm		
Outside diameter of solder pad	2.3 mm	Template aperture diameter	2.1 mm	
L1 in mm	38.5 mm	L1 in inches	1.516 inch	
Number of rows	1	Pin series quantity	1	
Touch-safe protection acc. to DIN VDE	Safe from back-of-hand	Touch-safe protection acc. to DIN VDE		
57 106	touch	0470	IP 10	
Volume resistance	≤5 mΩ	Can be coded	Yes	
Plugging force/pole, max.	6 N	Pulling force/pole, max.	6 N	

#### **Material data**

Insulating material	LCP GF	Colour	black
Colour chart (similar)	RAL 9011	Insulating material group	Illa
Comparative Tracking Index (CTI)	≥ 175	Moisture Level (MSL)	1
UL 94 flammability rating	V-0	Contact material	CuSn
Contact surface	tinned	Layer structure of solder connection	23 µm Ni / 57 µm Sn
Layer structure of plug contact	23 µm Ni / 57 µm Sn	Storage temperature, min.	-40 °C
Storage temperature, max.	70 °C	Operating temperature, min.	-50 °C
Operating temperature, max.	100 °C	Temperature range, installation, min.	-30 °C
Temperature range, installation, max.	100 °C		

#### Rated data acc. to IEC

tested acc. to standard		Rated current, min. number of poles		
	IEC 60664-1, IEC 61984	(Tu=20°C)	15 A	
Rated current, max. number of poles (Tu=20°C)	12 A	Rated current, min. number of poles (Tu=40°C)	13 A	
Rated current, max. number of poles (Tu=40°C)	10 A	Rated voltage for surge voltage class / pollution degree II/2	320 V	
Rated voltage for surge voltage class / pollution degree III/2	160 V	Rated voltage for surge voltage class / pollution degree III/3	160 V	
Rated impulse voltage for surge voltage class/ pollution degree II/2	2.5 kV	Rated impulse voltage for surge voltage class/ pollution degree III/2	2.5 kV	
Rated impulse voltage for surge voltage class/ contamination degree III/3	2.5 kV	Short-time withstand current resistance	3 x 1s with 100 A	

**Technical data** 

#### SL-SMT 3.50/12/180G 3.2SN BK RL



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27-46-02-01

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Rated data acc. to CSA				
Institute (CSA)	SP:	Certificate No. (CSA)		
	0001/		200039-1176845	
Rated voltage (Use group B / CSA)	300 V	Rated voltage (Use group D / CSA)	300 V	
Rated current (Use group B / CSA)     10 A       Reference to approval values     Specifications are maximum values, details - see approval certificate.		Rated current (Use group D / CSA)	10 A	
Rated data acc. to UL 1059				
Institute (UR)	<b>A</b> 1	Certificate No. (UR)	E60693	
Rated voltage (Use group B / UL 1059)	300 V	Rated voltage (Use group D / UL 1059)	300 V	
Rated current (Use group B / UL 1059)	10 A	Rated current (Use group D / UL 1059)	10 A	
Reference to approval values	Specifications are maximum values, details - see approval certificate.			
Packing				
	Tome		45 mm	
Packaging VPE width	Tape	VPE length		
Tape depth (T2)	330 mm 16.5 mm	VPE height Tape width (W)	330 mm 56 mm	
Tape pocket depth (KO)	16 mm	Tape pocket height (A0)	7.8 mm	
Tape pocket width (B0)	43.7 mm	Tape pocket separation (P1)	16 mm	
Tape hole separation (E)	1.75 mm	Tape pocket separation (F)	26.2 mm	
Tape reel diameter $\emptyset$ (A)	330 mm	Surface resistance	$Rs = 10^9 - 10^{12} \Omega$	
Width Pick & Place Pad (W <sub>PPP</sub> )	6.8 mm	Length Pick & Place Pad (L <sub>PPP</sub> )	12.65 mm	
Diameter of the withdrawal surface (ø		Protrusion 1 Pick & Place Pad (L <sub>01 (PPP)</sub> )		
D <sub>max</sub> )	5 mm		2.7 mm	
Protrusion 2 Pick & Place Pad (P <sub>02 (PPP)</sub> )	2.5 mm			
Classifications				
<b>FTIM</b> 0.0	5000007		5000007	
ETIM 6.0	EC002637	ETIM 7.0	EC002637	
ECLASS 9.0	27-44-04-02	ECLASS 9.1	27-44-04-02	

ECLASS 11.0

ECLASS 10.0

27-44-04-02





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Important note	
IPC conformity	Conformity: The products are developed, manufactured and delivered according international recognized standards and norms and comply with the assured properties in the data sheet resp. fulfill decorative propertie in accordance with IPC-A-610 "Class 2". Further claims on the products can be evaluated on request.
Notes	Gold-plated contact surfaces on request
	Rated current related to rated cross-section & min. No. of poles.
	• Diameter of solder eyelet D = 1.4+0.1mm
	• Solder eyelet diameter $D = 1.5 + 0.1 \text{ mm}$ , from 9 poles
	• P on drawing = pitch
	<ul> <li>Rated data refer only to the component itself. Clearance and creepage distances to other components are to be designed in accordance with the relevant application standards.</li> </ul>
	• Long term storage of the product with average temperature of 50 °C and average humidity 70%, 36 months
Approvals	
Approvals	
ROHS	Conform
UL File Number Search	E60693
Downloads	
Approval/Certificate/Document of Conformity	Declaration of the Manufacturer
Engineering Data	STEP

## Drawings

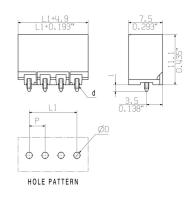


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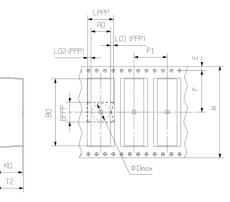
#### **Dimensional drawing**



#### **Dimensional drawing**

# 

#### Dimensional drawing



DIRECTION OF UNREELING

#### **Example of use**



#### Dimensions without tolerances are no check dimensions

0.0

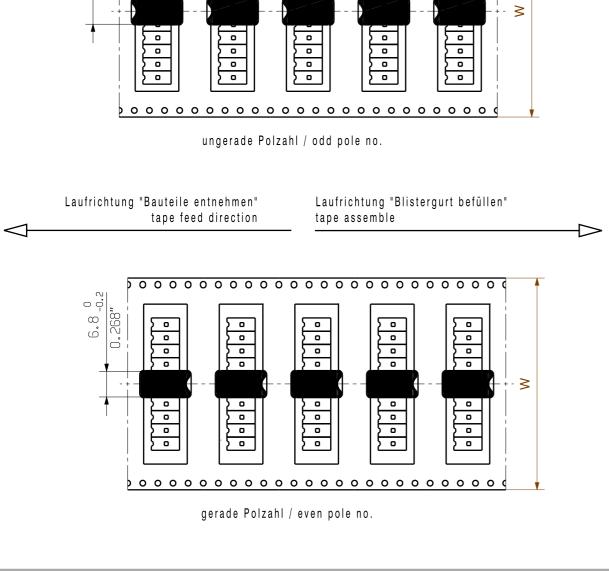
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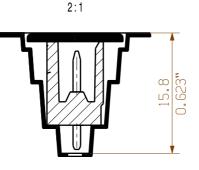
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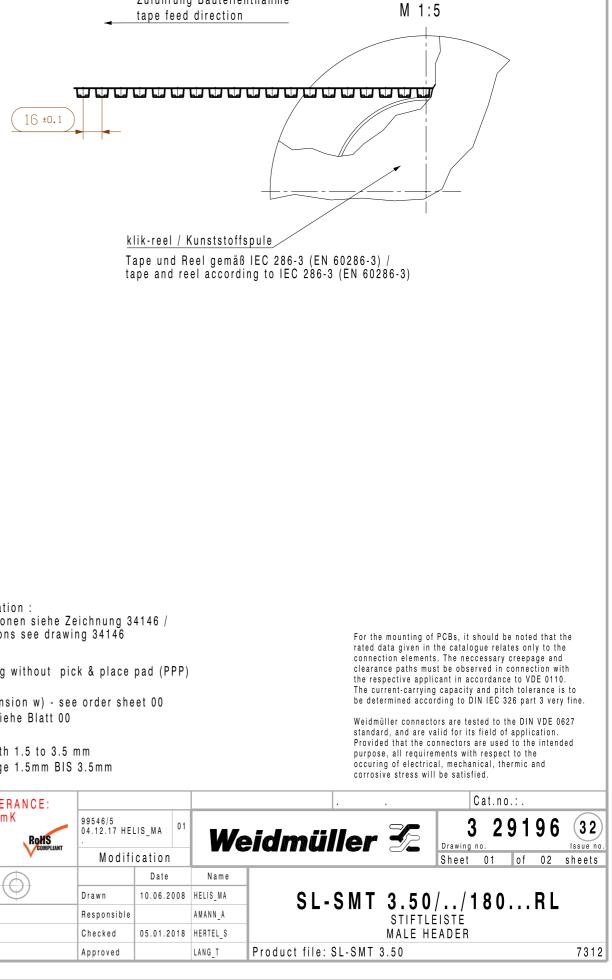
Zuführung Bauteilentnahme



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Hinweis / information : weitere Informationen siehe Zeichnung 34146 / further informations see drawing 34146

- \* supply/ equipping without pick & place pad (PPP)
- tape width (dimension w) see order sheet 00 tape Breite W - siehe Blatt 00

tape for pin length 1.5 to 3.5 mm Tape für Stiftlänge 1.5mm BIS 3.5mm

	GENERAL TOLERANCE:					
	DIN ISO 2768-mK	99546/5 04.12.17 HELIS_MA		01	We	
		Modification				
			Date		Name	
		Drawn	10.06.2	008	HELIS_MA	
		Responsible			AMANN_A	
	Scale: 2/1	Checked	05.01.2	018	HERTEL_S	
	Supersedes: .	Approved			LANG_T	

## Wave Solder Profile

#### **Recommended wave solderding profiles**

## Weidmüller 🟵

#### Weidmüller Interface GmbH & Co. KG

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**Double Wave:** 

Single Wave:



#### Wave soldering profiles

Wired connection elements should be processed in accordance with the DIN EN 61760-1 standard. We have included two recommendations for practical wave soldering profiles, with which Weidmüller PCB terminals and connectors are qualified.

When choosing a suitable profile for your application, the following factors also need to be considered:

- PCB thickness
- Proportion of Cu in the layers
- Single/double-sided assembly
- Product range
- Heating and cooling rates

The single and double wave profiles each indicate the recommended operating range, including the maximum soldering temperature of 260°C. In practice, the maximum soldering temperature is quite often well below the above maximum profile.

## **Reflow Solder Profile**

#### **Recommended reflow soldering profile**



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Time [sec]

#### **Reflow soldering profile**

The perfect soldering profile for SMT Surface Mount Technology is one the most exiting question in SMT production. But there are more than one correct answer: The diagram of temperature-on-time is related to processing features of solder paste and to maximum load of components.

We have to consider the following parameters:

- Time for pre heating
- Maximum temperature
- Time above melting point
- Time for cooling
- Maximum heating rate
- · Maximum cooling rate

We recommend a typical solder profile with associated process limits. With preheating components and board are prepared smoothly for the solder phase. Heating rate is typically  $\leq +3$ K/s. In parallel the solder paste is ,activated'. The time above melting point of 217°C the paste gets liquid and components and boards begin to connect. The maximum temperature of 245°C to 254°C should stay between 10 and 40 seconds. In the cooling phase at  $\geq$  -6K/s solder is cured. Board and components cool down while avoiding cold cracks.